ABSTRACT

SEMICONDUCTOR PACKAGE LOADING APPARATUS AND METHOD

The present invention provides a semiconductor package loading apparatus and method. The semiconductor package loading apparatus includes at least one transfer picker, a transfer block, and a pusher. The transfer pickers pick up a semiconductor package and transfer the semiconductor package in one direction. The transfer block has a package seating part where the semiconductor package picked up by the transfer picker is seated and one or more return spaces on an upper portion thereof, and is orthogonally movable with respect to a transfer direction of the transfer picker. The pusher loads the semiconductor package seated in the transfer block into a tube and linearly reciprocating. Here, the pusher loads the semiconductor package into the tube through the package seating part and moves backward through the return space as the transfer block moves after the semiconductor package is loaded into the tube.

Fig. 1